



THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/831,763
Filed: May 11, 2001
Inventor(s): Heinrich Meyer et al.
For: Method of Galvanically
Forming Conductor
Structures of High-Purity
Copper in the Production
of Integrated Circuits
Examiner: Mutschler, Brian L.
Art Unit: 1753

Attorney Docket No.: 071-01

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

<p>CERTIFICATE OF MAILING DATE OF DEPOSIT: May 10, 2004 I hereby certify that this correspondence is being deposited with the United States Postal Service, postage paid, as first class mail under 37 C.F.R. §1.8, on the date indicated above and is addressed to Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450. Name of person mailing paper or fee: Ourmazd S. Ojan Signature: <u><i>Ourmazd S. Ojan</i></u></p>
--

AMENDMENT

Dear Sir:

This communication is responsive to the Final Office Action mailed on January 23, 2004, and having a three-month shortened statutory period for response that expired on April 23, 2004. The period for response is extended by the attached petition for a one-month extension of time and the accompanying check for \$110.00. This amendment is being filed within the extended period for response.

In the event that additional fees are required with respect to this communication, the Commissioner is hereby authorized to charge any such fees, or credit any overpayment, to Paul & Paul deposit account number 16-0750.